

Webinar Talk on “Why Electronic Packaging Matters: Influence of Engineers as an IP “Differentiator”?”

Jointly organised by:

Mechanical Engineering Technical Division, Electronic Engineering Technical Division & IMechE Malaysia Branch

Date: 18th February 2023 (Saturday) | Time: 9am to 11am | Venue: Virtual Platform – Zoom



Speaker-1:
Dr. Wong Shaw Fong



Speaker-2:
Dr. Lee Yuan Thing

REGISTRATION FEES

IEM Students: Free

IEM Members/IMechE Members:
RM15 (Online) / RM20 (Offline)

Non-IEM Members: RM70

BEM Approved CPD/PDP Hours: 2
Ref No: IEM23/HQ/022/T (w)

Synopsis

The semiconductor package is evolving in a very fast pace lately. Many research institution and industries are aggressively working towards advanced packaging solution for functional integration. This advanced packaging is predicted would account for >50% of all packaging services by 2030. Segmentation in packaging design by field application used to be a key enabler for silicon solution. However, innovations in packaging intellectual property (IP) have been constantly re-invented, exploring the potential options for extremely high volumes. This likely to pay back the enormous up-front investment and therefore, packaging scaling is becoming critical and more economical to achieve. Though, and in many new or existing IoT, client and server applications, packaging is becoming a key differentiator. The packaging technology strategies must accommodate cost effective solutions using standard packaging technologies while still push for significant product advancement. The differentiator examples include ultrathin and small packages for mobility, large and thick packages for extreme high density and functionality applications. Also, our industry is heading toward more and more heterogeneous integration, enabling in packaging process and assembly execution mostly driven to further benefit with the higher volumes and scaling of production/ market share.

This talk will share the overview of electronic packaging design, product or market segmentation and address the strategies to overcome the diverse and complex demands. Some possible differentiator opportunities include design tool, material enhancement, assembly advancement and development ecosystem, which must be revisited at every step of the flow, from initial concept and design all the way through to manufacturing. The sharing also will cover some of the latest focus by Malaysia local universities researchers as well as the critical work by industry and manufacturing sites.

Hence, fasten your seatbelt – don't miss the wave of electronic packaging engineer as the IP differentiator!

Ir. Dr. Aidil Chee Tahir

Chairman

Mechanical Engineering Technical Division, IEM

Ir. Dr. Mui Kai Yin

Chairman

Electronic Engineering Technical Division, IEM

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